



Semiconductor CMP Pad Technology Company NexPlanar Opens Representative Office in Taiwan

Hillsboro, Oregon, January 18, 2010

In response to growing business activity in Taiwan and in South East Asia, NexPlanar has established a representative office in Taipei.

“We have been very pleased with the commercial acceptance of our CMP polishing pads. In particular the customer interest and feedback on the performance of our [newly launched](#) Element™ line of pads has exceeded our expectations. The establishment of the Taiwan representative office complements our established network of distributors throughout Asia and will aid us in supporting our growing customer base,” said Haluk Oran, VP of Business Development.

About NexPlanar Corporation

NexPlanar builds the next generation of chemical mechanical planarization (CMP) pads for the semiconductor device industry. NexPlanar uses proprietary “nano-domain” technology that improves planarity and across-wafer uniformity and can be utilized to customize the CMP pads for specific applications. NexPlanar’s “nano-lubricants” and patented molded groove technologies allow for low stress CMP (required for the most advanced CMP applications), result in an order of magnitude fewer defects, low slurry consumption processing and lower overall cost of ownership. See www.nexplanar.com.

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